

SMT ADHESIVE - Low Temp. Curable Type

JU - 95

■ Features

1. Designed for low temperature curing use.
2. Excellent dispensability.
3. Fine dot profile.



■ Specifications

Before curing	Application		Dispenser
	Composition		Epoxy
	State • Color		Paste, Red
	Specific gravity		1.22±0.05
	Viscosity (Pa.s • 20°C)		80
	Thixotropy (20°C)		7.0±0.05
	Non-volatile (105°C • 3 hr)		>99
	Shelf life	Below 5°C	4 months
After curing	State • Color		Polymerized, dark red
	Bonding strength	2125 chip condenser	>2.0kg
	Copper plate corrosion (40°C× 95%RH×96hr)		Passed
	Heat resistivity (250°C × 10sec.)		Passed
	Surface insulation resistant	Initial value (Ω)	> 1 × 10 ¹²
		40°C, 95%RH× 96hr (Ω)	> 1 × 10 ¹⁰
	Water absorption(%)		< 0.5
Linear expansion coefficient (cm/cm•°C)		8 × 10 ⁻⁵	

■ Dispensing temperature

Optimum results will be obtained at a constant controlled temperature of 35~45°C.

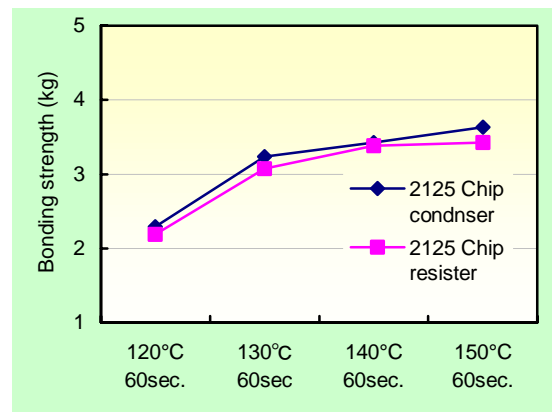
■ Curing condition

100°C × over 90sec.
110°C × over 60sec

■ Packaging

Available in 300gs tube, 1kg jar and various types of syringes (5cc, 10cc, 20cc, 30cc)

■ Bonding strength



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